



SOT1571-6

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.5 mm body; 4.4 mm x 4.4 mm exposed pad

20 April 2022

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP48
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-03-2022
Manufacturer package code	98ASA00945D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
seated height	-	1.5	-	mm
package height	-	1.4	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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2 Package outline

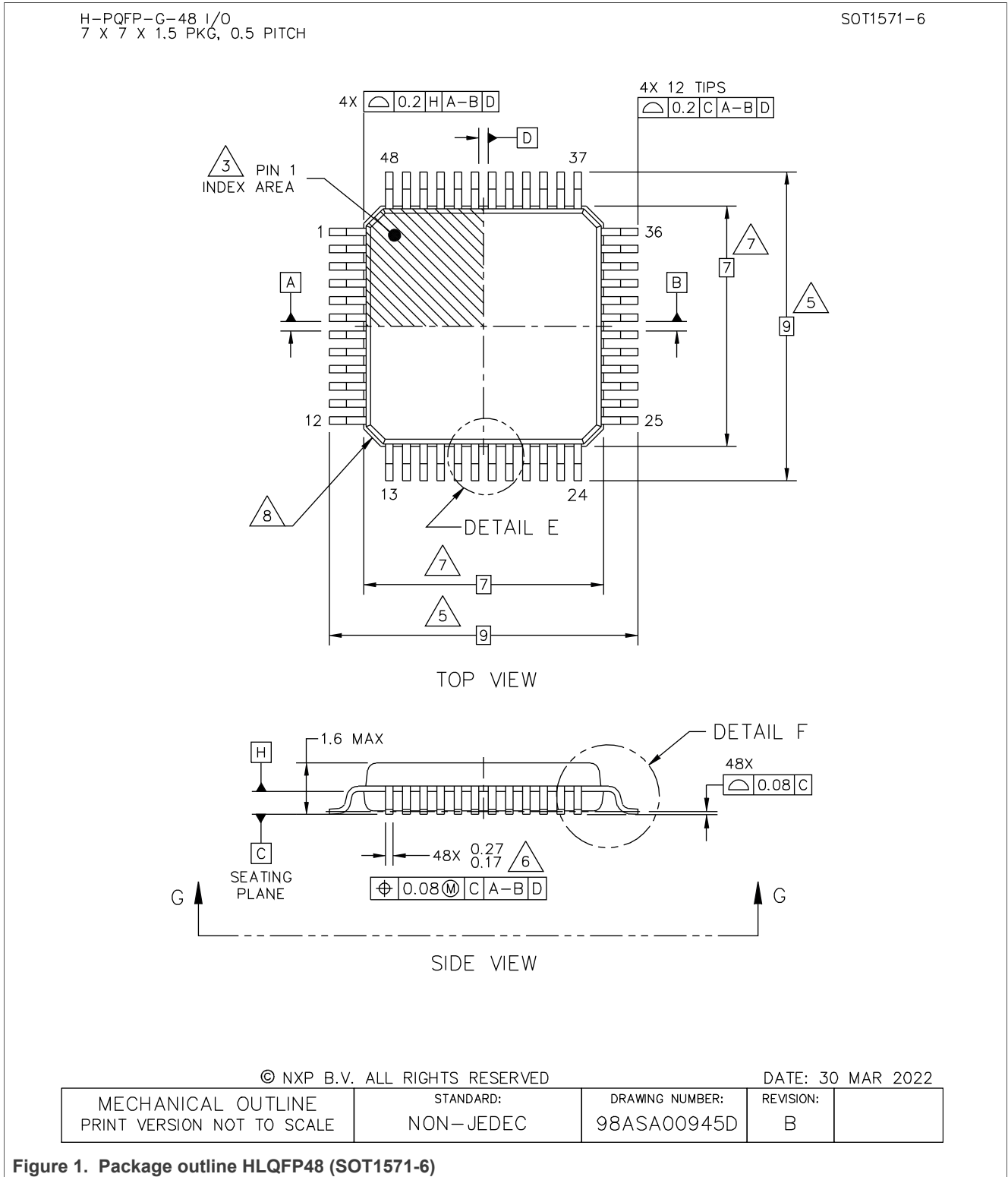
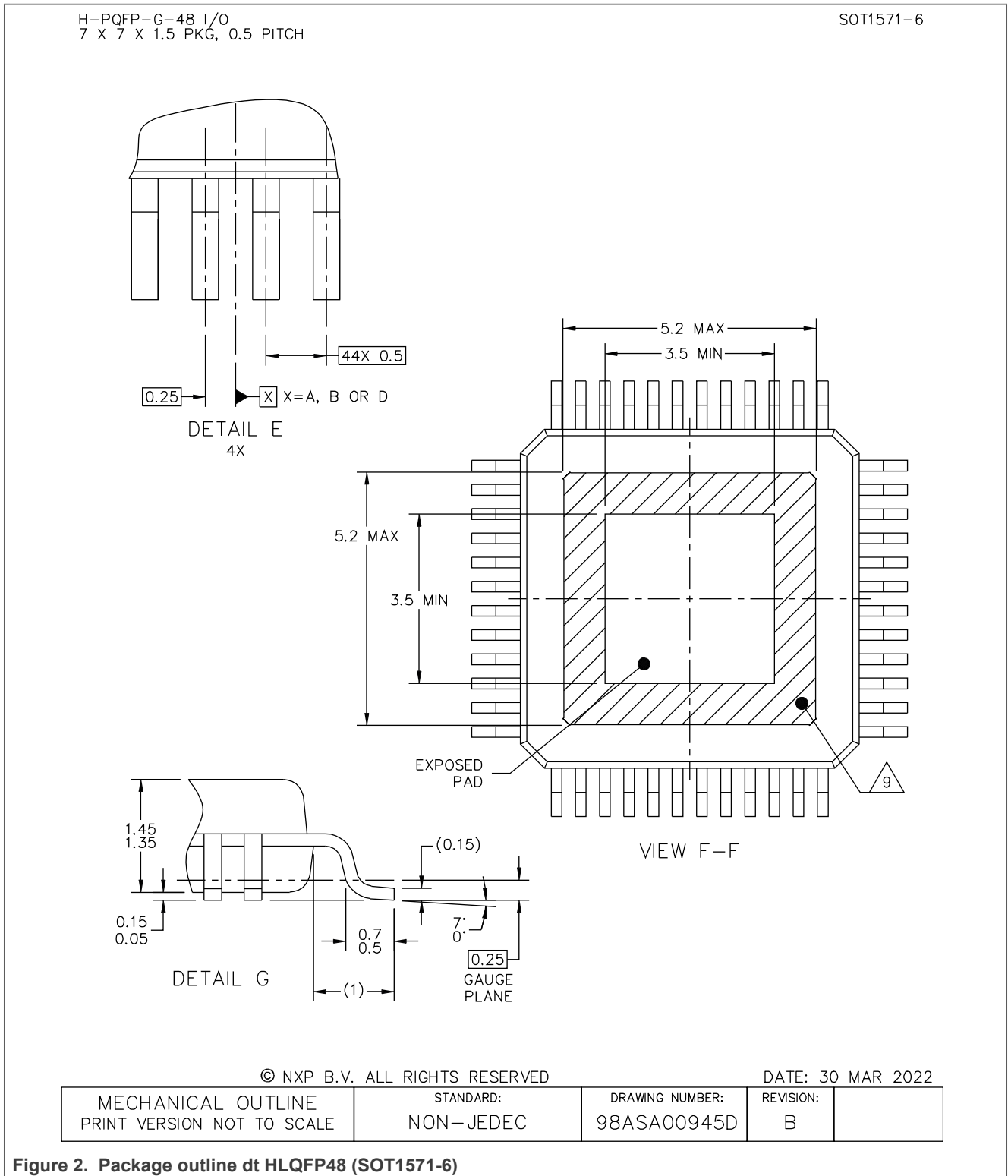


Figure 1. Package outline HLQFP48 (SOT1571-6)

HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.5 mm body; 4.4 mm x 4.4 mm exposed pad



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H-PQFP-G-48 1/0
7 X 7 X 1.5 PKG, 0.5 PITCH

SOT1571-6

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. HATCHED AREA REPRESENTS POSSIBLE MOLD FLASH ON EXPOSED PAD.
10. KEEP OUT ZONE REPRESENTS AREA ON PCB THAT MUST NOT HAVE ANY EXPOSED METAL (TRACE/VIA) FOR PCB ROUTING DUE TO THE POSSIBILITY OF SHORTING TO TIE BAR/EXPOSED PAD.

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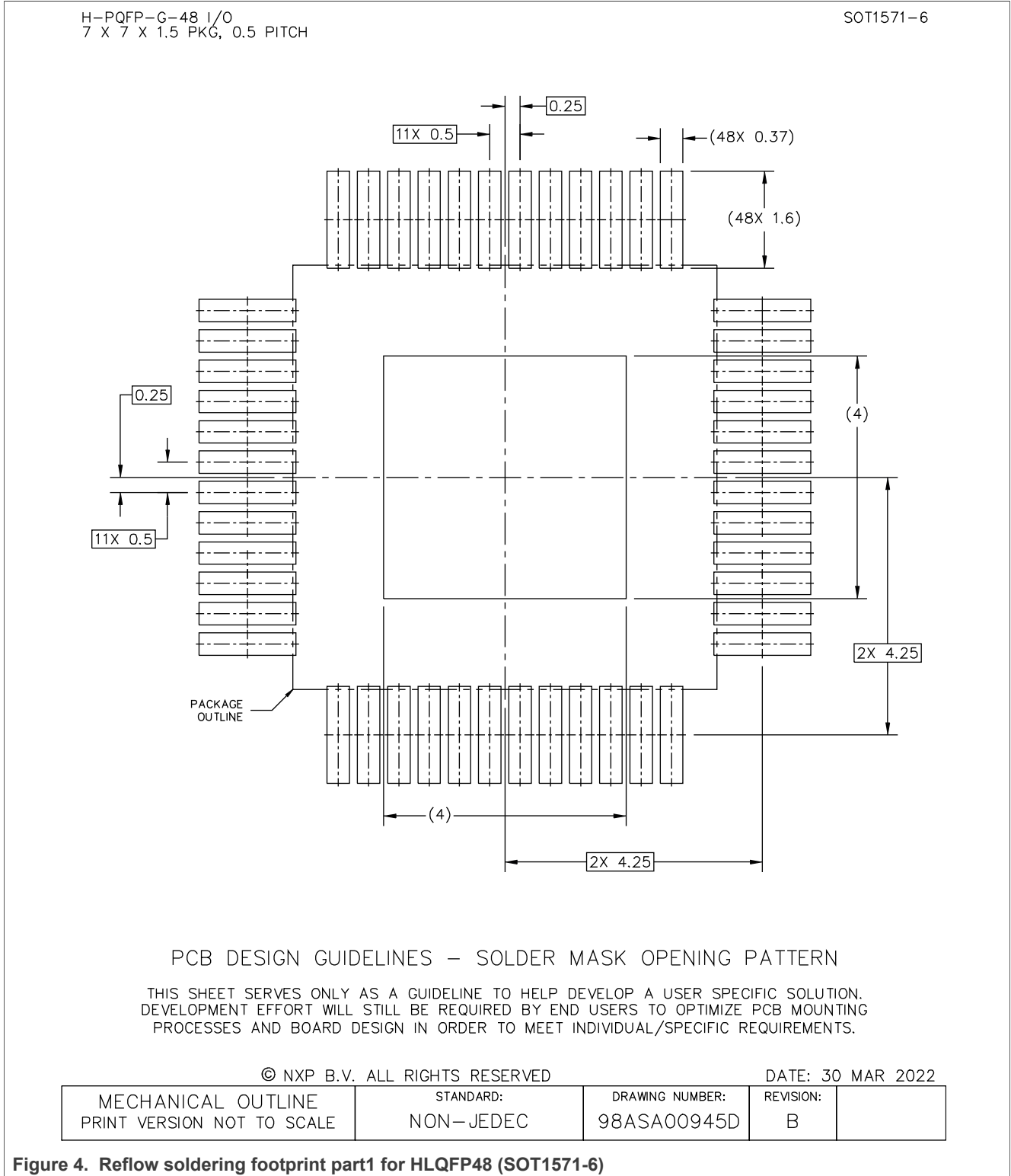
DATE: 30 MAR 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA00945D	REVISION: B	
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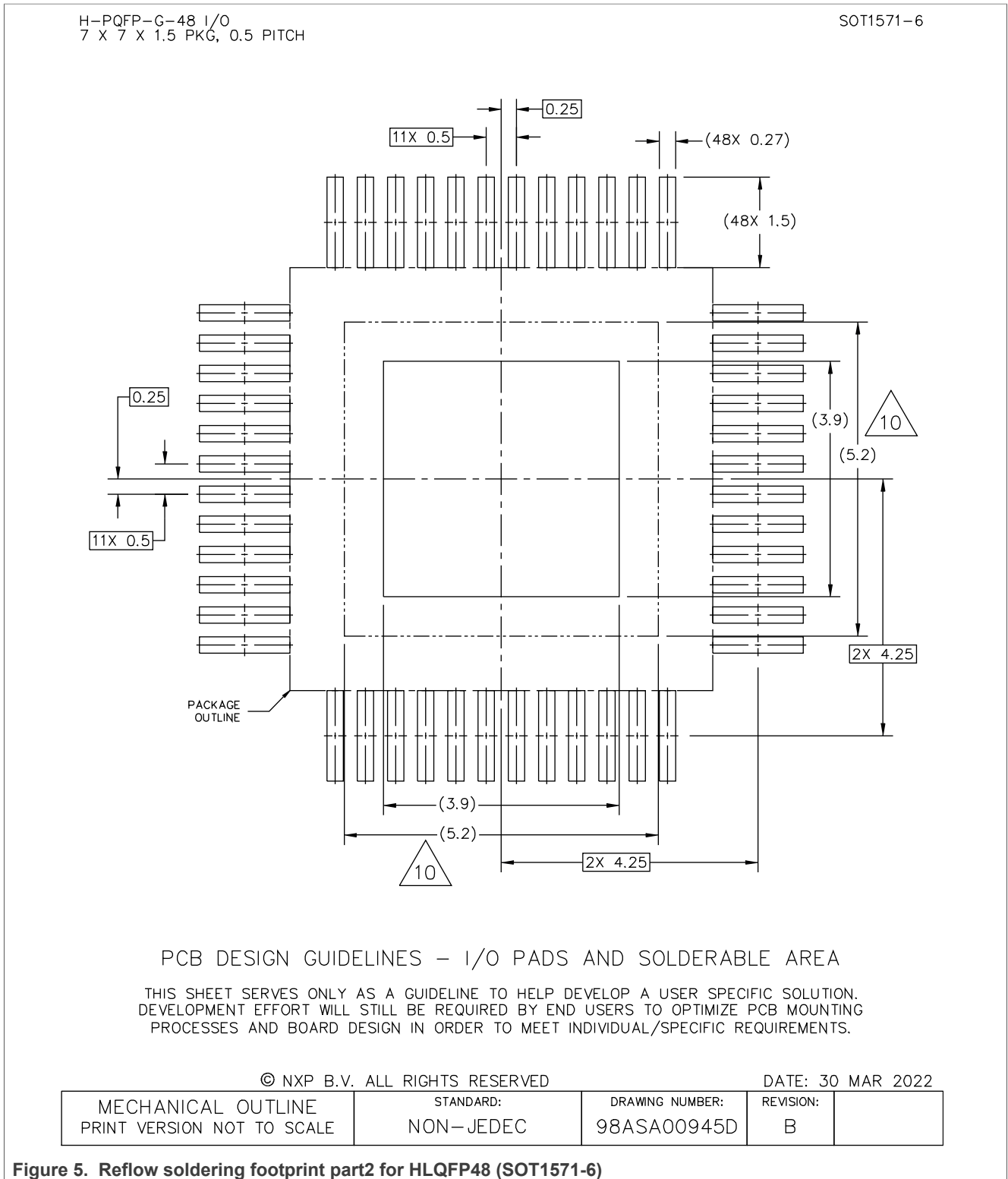
Figure 3. Package outline note HLQFP48 (SOT1571-6)

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3 Soldering



HLQFP48, plastic, thermal enhanced low profile quad flat package; 48 terminals; 0.5 mm pitch; 7 mm x 7 mm x 1.5 mm body; 4.4 mm x 4.4 mm exposed pad



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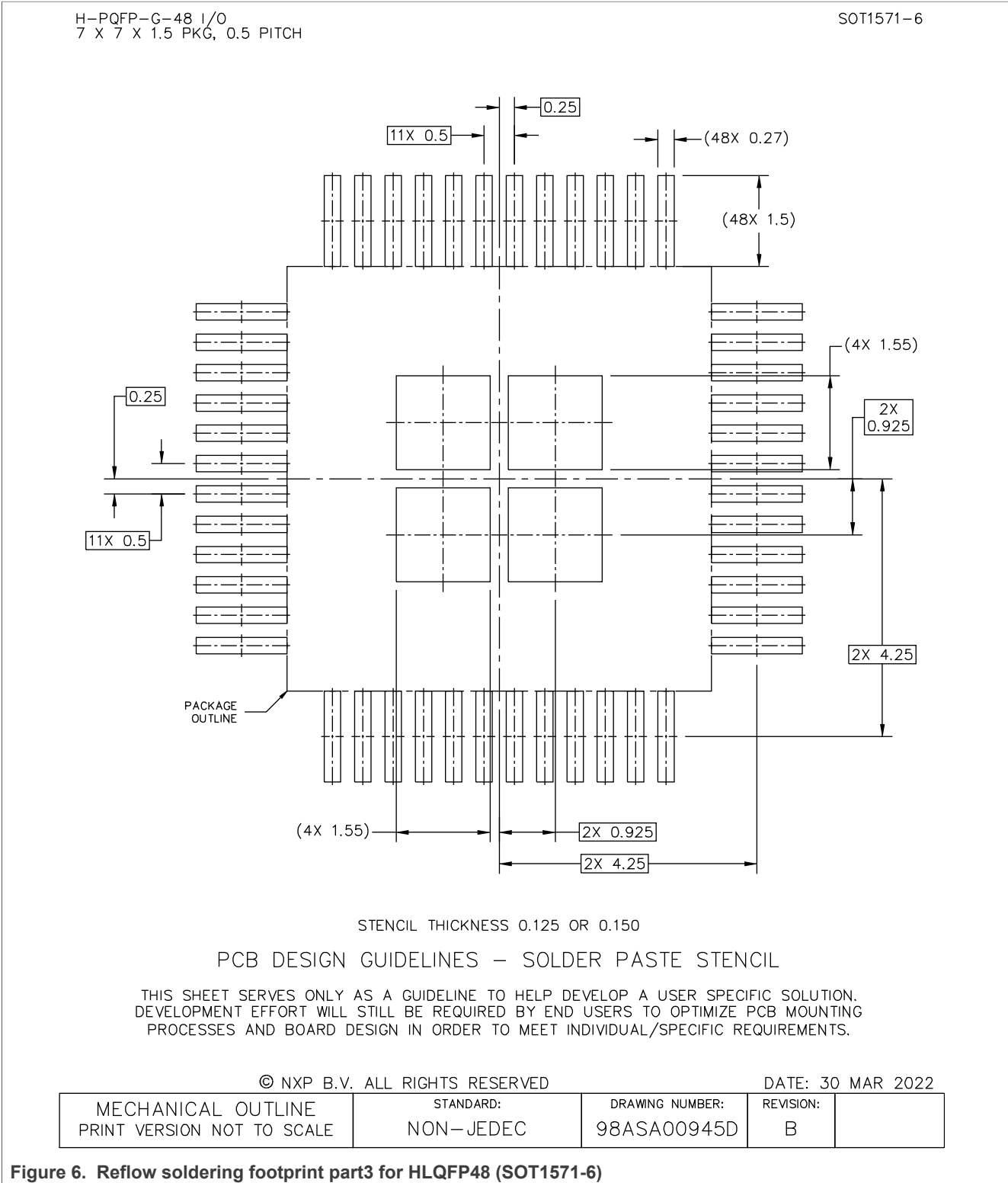


Figure 6. Reflow soldering footprint part3 for HLQFP48 (SOT1571-6)

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4 Legal information

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